

May 1997

### Features

- 45A, 20V
- $r_{DS(ON)} = 0.022\Omega$
- *Temperature Compensating PSPICE Model*
- Can be Driven Directly from CMOS, NMOS, and TTL Circuits
- Peak Current vs Pulse Width Curve
- UIS Rating Curve
- 175°C Operating Temperature

### Ordering Information

PART NUMBER	PACKAGE	BRAND
RFP45N02L	TO-220AB	FP45N02L
RF1S45N02L	TO-262AA	F45N02L
RF1S45N02LSM	TO-263AB	F45N02L

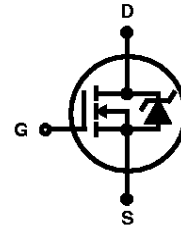
NOTE: When ordering, use the entire part number. Add the suffix, 9A, to obtain the TO-263AB variant in tape and reel, e.g. RF1S45N02LSM9A.

### Description

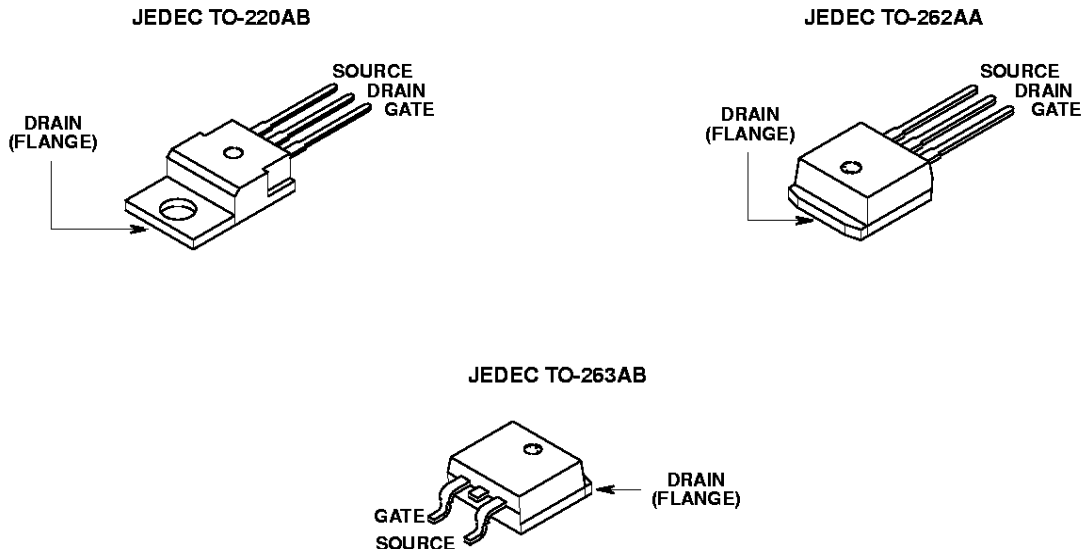
The RFP45N02L, RF1S45N02L, and RF1S45N02LSM are N-Channel power MOSFETs manufactured using the MegaFET process. This process, which uses feature sizes approaching those of LSI circuits, gives optimum utilization of silicon, resulting in outstanding performance. They were designed for use in applications such as switching regulators, switching converters, motor drivers and relay drivers. These transistors can be operated directly from integrated circuits.

Formerly developmental type TA49243.

### Symbol



### Packaging



## RFP45N02L, RF1S45N02L, RF1S45N02LSM

### Absolute Maximum Ratings $T_C = 25^\circ\text{C}$ Unless Otherwise Specified

	RFP45N02L, RF1S45N02L, RF1S45N02LSM	UNITS
Drain to Source Voltage	20	V
Drain to Gate Voltage	20	V
Gate to Source Voltage	$\pm 10$	V
Drain Current		
Continuous	45	A
Pulsed Drain Current	Refer to Peak Current Curve	
Pulsed Avalanche Rating	Refer to UIS Curve	
Power Dissipation	90	W
Derate Above $25^\circ\text{C}$	0.606	$\text{W}/^\circ\text{C}$
Operating and Storage Temperature	-55 to 175	$^\circ\text{C}$
Soldering Temperature of Leads for 10s	260	$^\circ\text{C}$

*CAUTION: Stresses above those listed in "Absolute Maximum Ratings" may cause permanent damage to the device. This is a stress only rating and operation of the device at these or any other conditions above those indicated in the operational sections of this specification is not implied.*

### Electrical Specifications $T_C = 25^\circ\text{C}$ , Unless Otherwise Specified

PARAMETER	SYMBOL	TEST CONDITIONS	MIN	TYP	MAX	UNITS	
Drain to Source Breakdown Voltage	$BV_{DSS}$	$I_D = 250\mu\text{A}$ , $V_{GS} = 0\text{V}$	20	-	-	V	
Gate to Source Threshold Voltage	$V_{GS(TH)}$	$V_{GS} = V_{DS}$ , $I_D = 250\mu\text{A}$	1	-	2	V	
Zero Gate Voltage Drain Current	$I_{DSS}$	$V_{DS} = 20\text{V}$ , $V_{GS} = 0\text{V}$	$T_C = 25^\circ\text{C}$	-	-	1	$\mu\text{A}$
			$T_C = 150^\circ\text{C}$	-	-	50	$\mu\text{A}$
Gate to Source Leakage Current	$I_{GSS}$	$V_{GS} = \pm 10\text{V}$	-	-	$\pm 100$	nA	
Drain to Source On Resistance	$r_{DS(ON)}$	$I_D = 45\text{A}$ , $V_{GS} = 5\text{V}$	-	-	0.022	$\Omega$	
Turn-On Time	$t_{ON}$	$V_{DD} = 15\text{V}$ , $I_D \cong 45\text{A}$ , $R_L = 0.33\Omega$ , $V_{GS} = 5\text{V}$ , $R_{GS} = 5\Omega$	-	-	260	ns	
Turn-On Delay Time	$t_{d(ON)}$		-	15	-	ns	
Rise Time	$t_r$		-	160	-	ns	
Turn-Off Delay Time	$t_{d(OFF)}$		-	20	-	ns	
Fall Time	$t_f$		-	20	-	ns	
Turn-Off Time	$t_{OFF}$		-	-	60	ns	
Total Gate Charge	$Q_g(TOT)$		$V_{GS} = 0\text{V}$ to $10\text{V}$	$V_{DD} = 16\text{V}$ , $I_D \cong 45\text{A}$ , $R_L = 0.35\Omega$	-	50	60
Gate Charge at 5V	$Q_g(5)$	$V_{GS} = 0\text{V}$ to $5\text{V}$	-		30	36	nC
Threshold Gate Charge	$Q_g(TH)$	$V_{GS} = 0\text{V}$ to $1\text{V}$	-		1.5	1.8	nC
Input Capacitance	$C_{ISS}$	$V_{DS} = 15\text{V}$ , $V_{GS} = 0\text{V}$ , $f = 1\text{MHz}$	-	1300	-	pF	
Output Capacitance	$C_{OSS}$		-	724	-	pF	
Reverse Transfer Capacitance	$C_{RSS}$		-	250	-	pF	
Thermal Resistance Junction to Case	$R_{\theta JC}$		-	-	1.65	$^\circ\text{C}/\text{W}$	
Thermal Resistance Junction to Ambient	$R_{\theta JA}$		-	-	80	$^\circ\text{C}/\text{W}$	

### Source to Drain Diode Specifications

PARAMETER	SYMBOL	TEST CONDITIONS	MIN	TYP	MAX	UNITS
Source to Drain Diode Voltage	$V_{SD}$	$I_{SD} = 45\text{A}$	-	-	1.5	V
Reverse Recovery Time	$t_{rr}$	$I_{SD} = 45\text{A}$ , $dI_{SD}/dt = 100\text{A}/\mu\text{s}$	-	-	125	ns

Typical Performance Curves

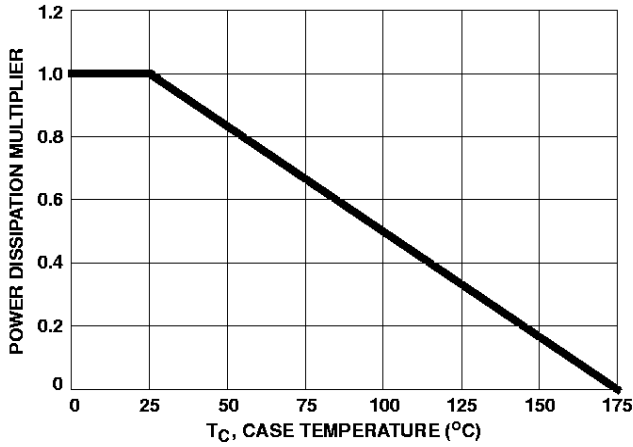


FIGURE 1. NORMALIZED POWER DISSIPATION vs TEMPERATURE DERATING

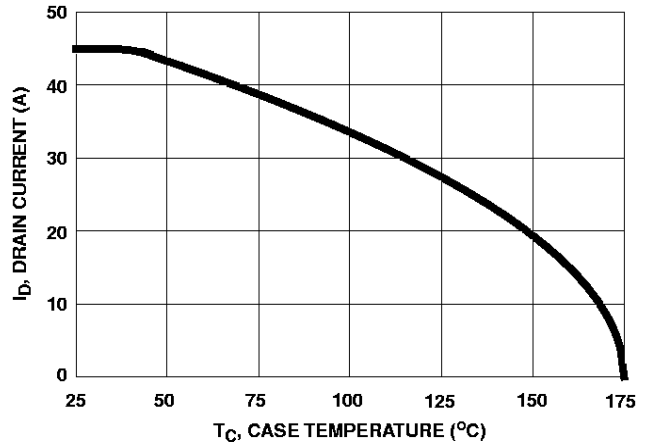


FIGURE 2. MAXIMUM CONTINUOUS DRAIN CURRENT vs CASE TEMPERATURE

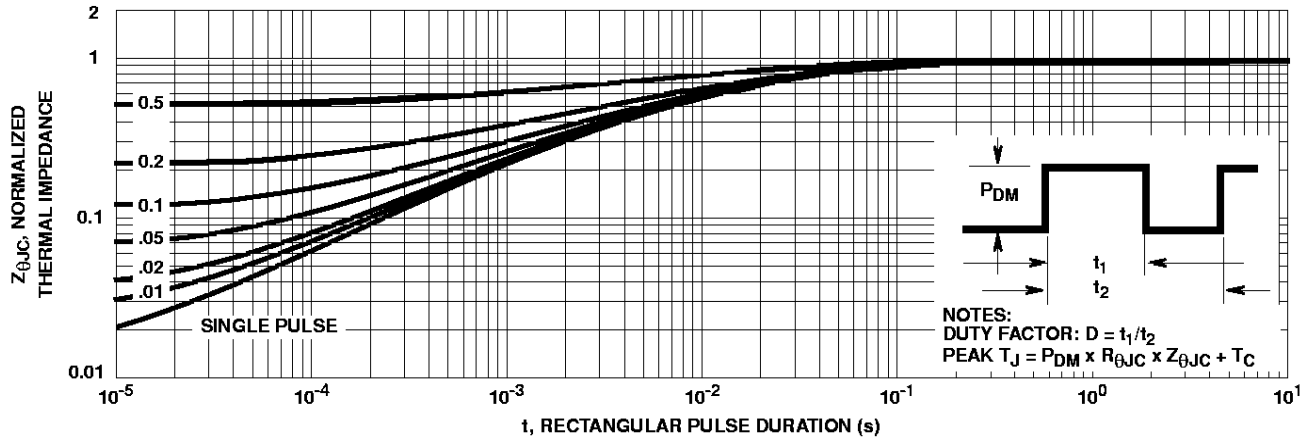


FIGURE 3. NORMALIZED MAXIMUM TRANSIENT THERMAL IMPEDANCE

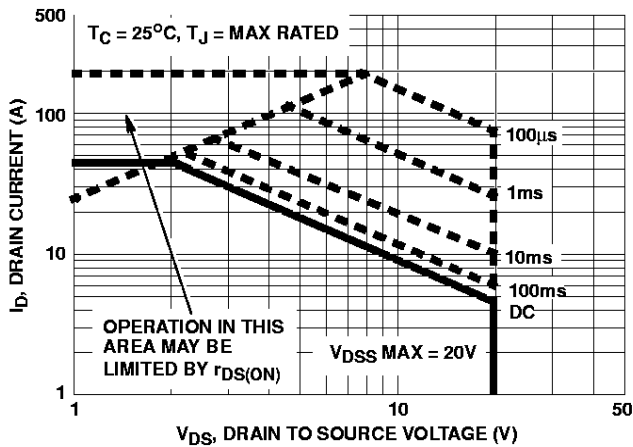


FIGURE 4. FORWARD BIAS SAFE OPERATING AREA

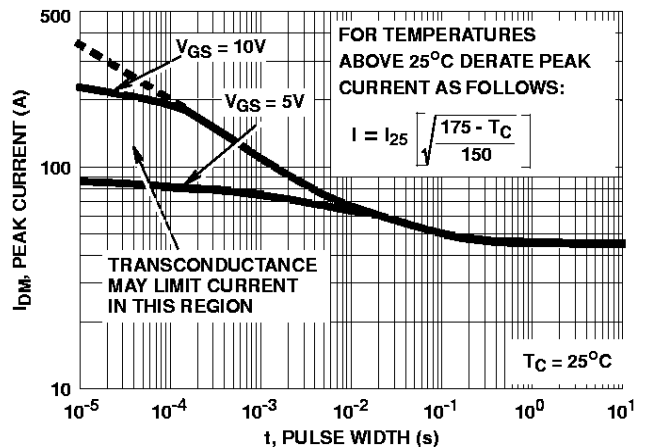
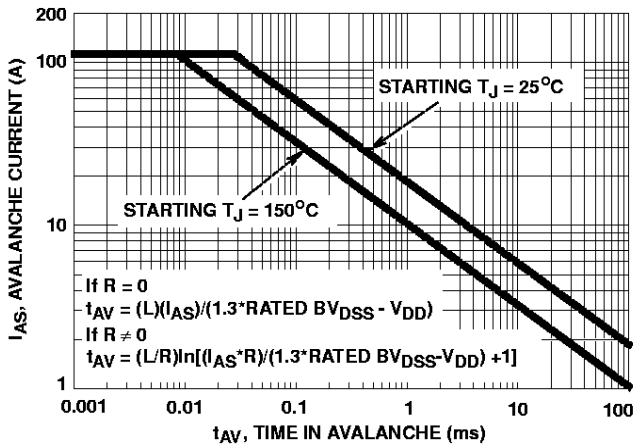


FIGURE 5. PEAK CURRENT CAPABILITY

Typical Performance Curves (Continued)



NOTE: Refer to Harris Application Notes AN9321 and AN9322.

FIGURE 6. UNCLAMPED INDUCTIVE SWITCHING

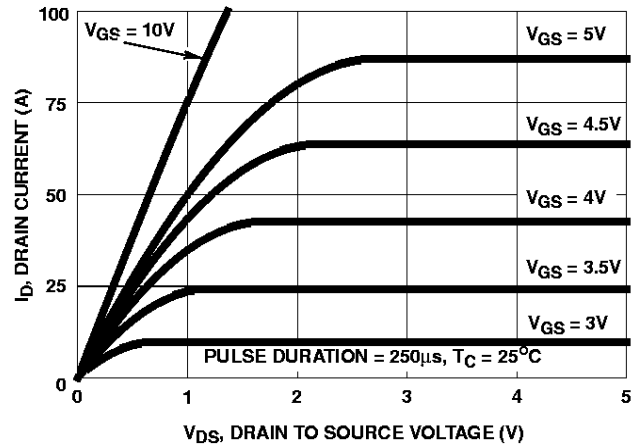


FIGURE 7. SATURATION CHARACTERISTICS

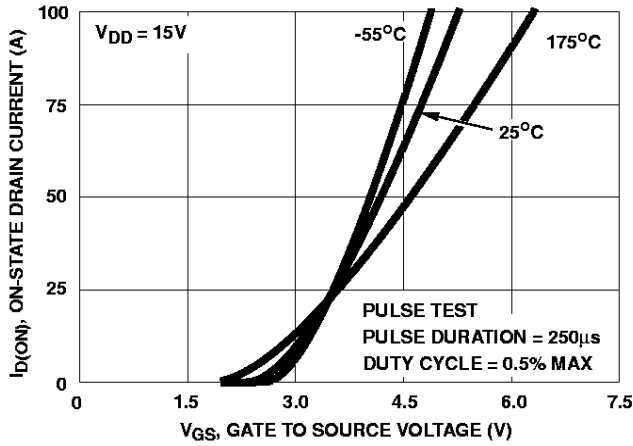


FIGURE 8. TRANSFER CHARACTERISTICS

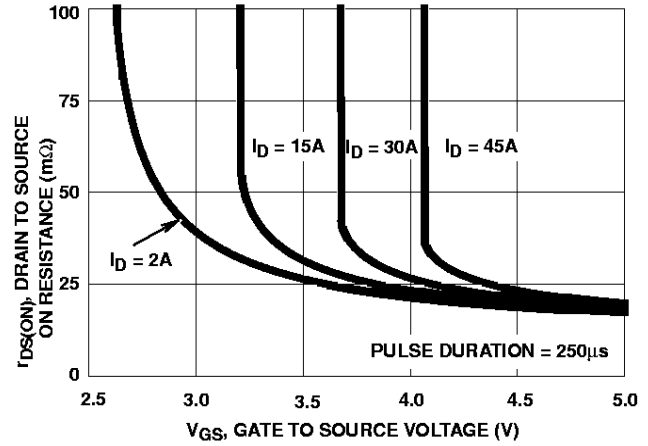


FIGURE 9. DRAIN TO SOURCE ON RESISTANCE vs GATE VOLTAGE AND DRAIN CURRENT

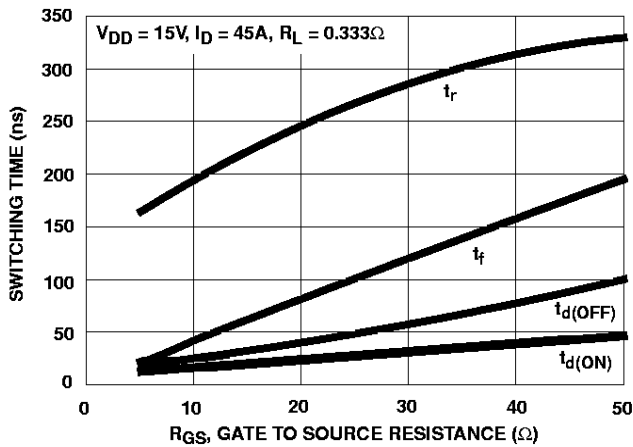


FIGURE 10. SWITCHING TIME AS A FUNCTION OF GATE RESISTANCE

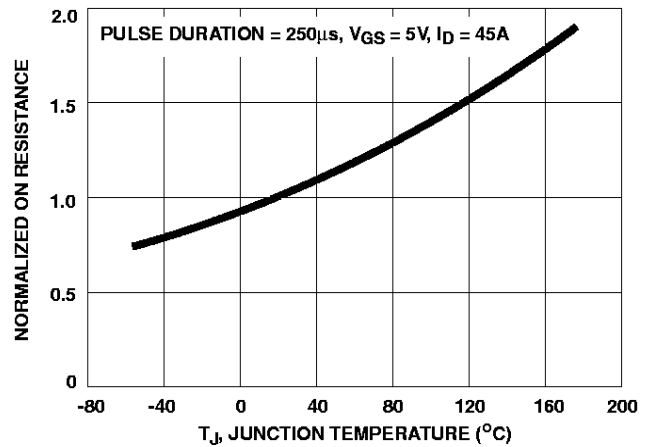


FIGURE 11. NORMALIZED DRAIN TO SOURCE ON RESISTANCE vs JUNCTION TEMPERATURE

Typical Performance Curves (Continued)

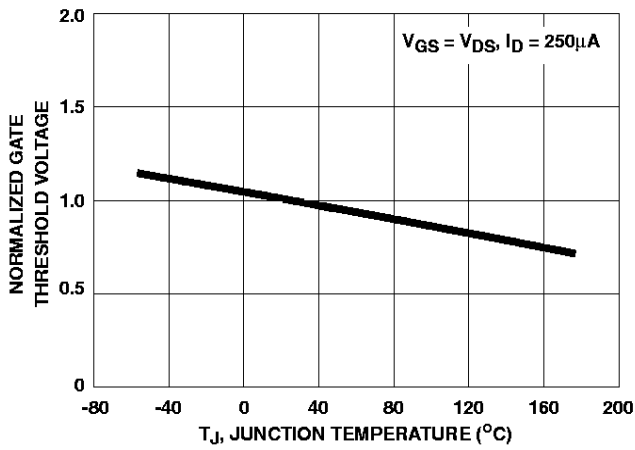


FIGURE 12. NORMALIZED GATE THRESHOLD VOLTAGE vs JUNCTION TEMPERATURE

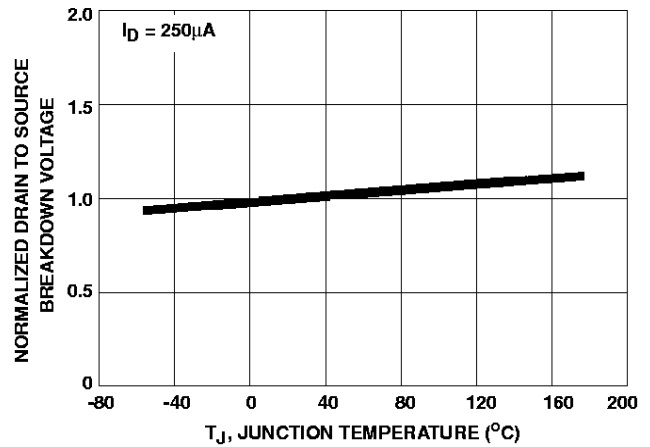


FIGURE 13. NORMALIZED DRAIN TO SOURCE BREAKDOWN VOLTAGE vs JUNCTION TEMPERATURE

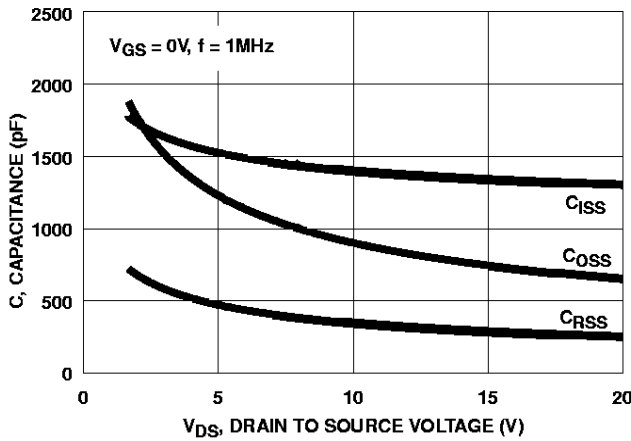
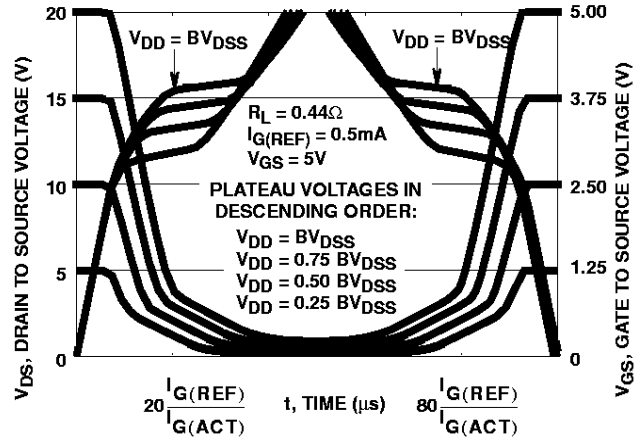


FIGURE 14. CAPACITANCE vs DRAIN TO SOURCE VOLTAGE



NOTE: Refer to Application Notes AN7254 and AN7260.  
FIGURE 15. NORMALIZED SWITCHING WAVEFORMS FOR CONSTANT GATE CURRENT

Test Circuits and Waveforms

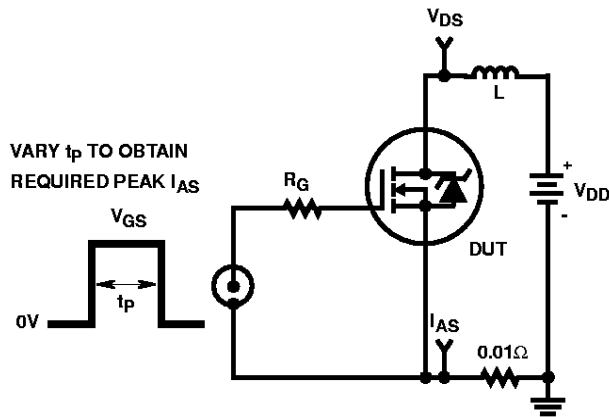


FIGURE 16. UNCLAMPED ENERGY TEST CIRCUIT

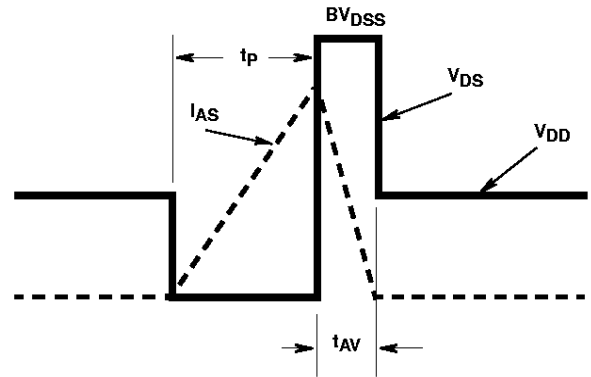


FIGURE 17. UNCLAMPED ENERGY WAVEFORMS

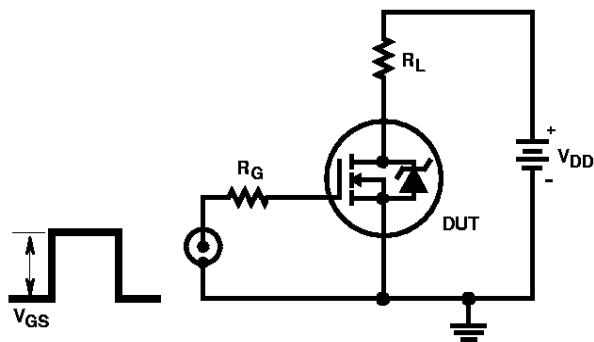


FIGURE 18. RESISTIVE SWITCHING TEST CIRCUIT

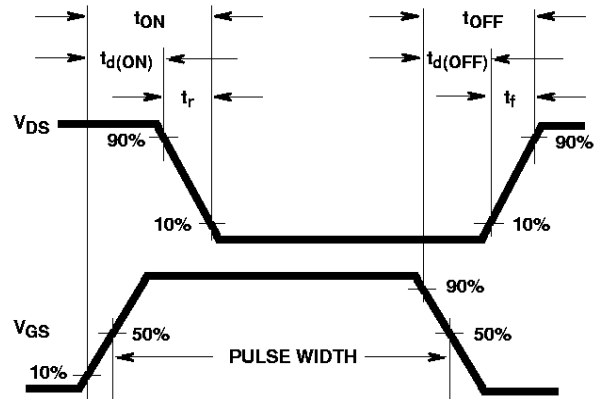


FIGURE 19. RESISTIVE SWITCHING WAVEFORMS

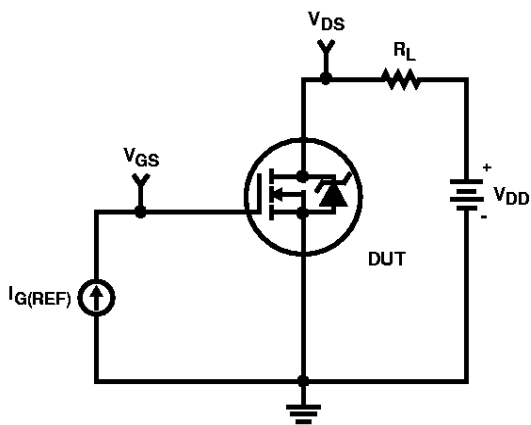


FIGURE 20. GATE CHARGE TEST CIRCUIT

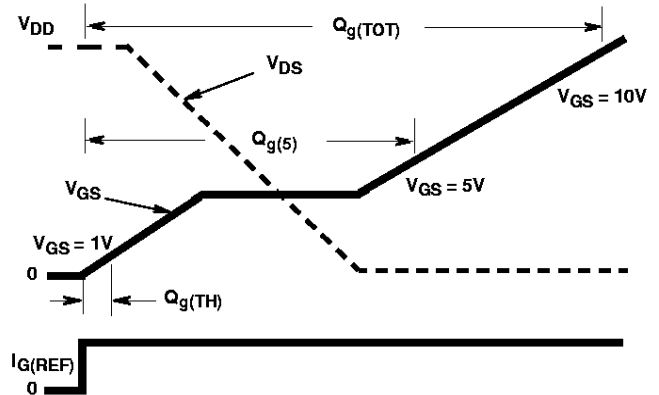


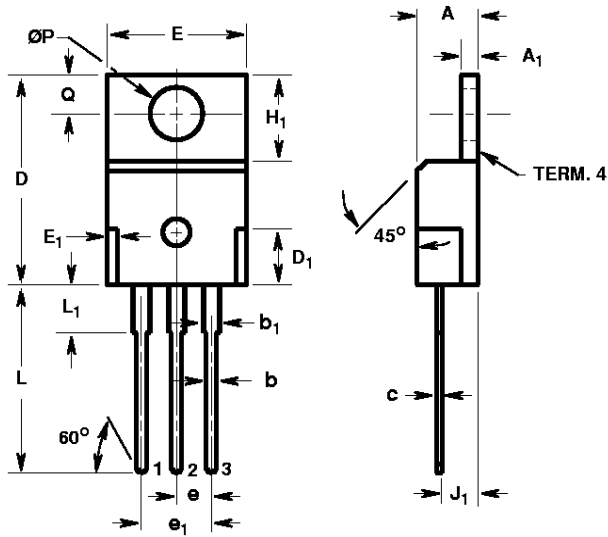
FIGURE 21. GATE CHARGE WAVEFORMS



RFP45N02L, RF1S45N02L, RF1S45N02LSM

**TO-220AB**

3 LEAD JEDEC TO-220AB PLASTIC PACKAGE



- Lead No. 1 - Gate
- Lead No. 2 - Drain
- Lead No. 3 - Source
- Term 4. - Drain

SYMBOL	INCHES		MILLIMETERS		NOTES
	MIN	MAX	MIN	MAX	
A	0.170	0.180	4.32	4.57	-
A <sub>1</sub>	0.048	0.052	1.22	1.32	-
b	0.030	0.034	0.77	0.86	3, 4
b <sub>1</sub>	0.045	0.055	1.15	1.39	2, 3
c	0.014	0.019	0.36	0.48	2, 3, 4
D	0.590	0.610	14.99	15.49	-
D <sub>1</sub>	-	0.160	-	4.06	-
E	0.395	0.410	10.04	10.41	-
E <sub>1</sub>	-	0.030	-	0.76	-
e	0.100 TYP		2.54 TYP		5
e <sub>1</sub>	0.200 BSC		5.08 BSC		5
H <sub>1</sub>	0.235	0.255	5.97	6.47	-
J <sub>1</sub>	0.100	0.110	2.54	2.79	6
L	0.530	0.550	13.47	13.97	-
L <sub>1</sub>	0.130	0.150	3.31	3.81	2
$\varnothing P$	0.149	0.153	3.79	3.88	-
Q	0.102	0.112	2.60	2.84	-

NOTES:

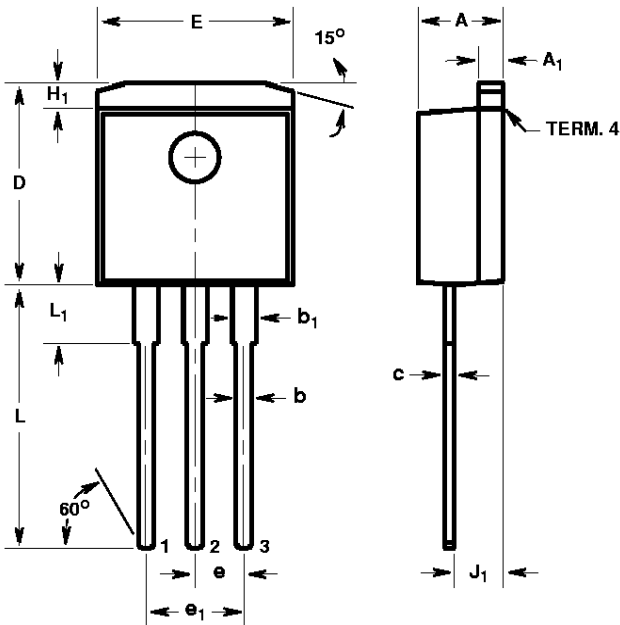
1. These dimensions are within allowable dimensions of Rev. J of JEDEC TO-220AB outline dated 3-24-87.
2. Lead dimension and finish uncontrolled in L<sub>1</sub>.
3. Lead dimension (without solder).
4. Add typically 0.002 inches (0.05mm) for solder coating.
5. Position of lead to be measured 0.250 inches (6.35mm) from bottom of dimension D.
6. Position of lead to be measured 0.100 inches (2.54mm) from bottom of dimension D.
7. Controlling dimension: Inch.
8. Revision 1 dated 1-93.



RFP45N02L, RF1S45N02L, RF1S45N02LSM

**TO-262AA**

3 LEAD JEDEC TO-262AA PLASTIC PACKAGE



- Lead No. 1 - Gate
- Lead No. 2 - Drain
- Lead No. 3 - Source
- Term 4. - Drain

SYMBOL	INCHES		MILLIMETERS		NOTES
	MIN	MAX	MIN	MAX	
A	0.170	0.180	4.32	4.57	-
A <sub>1</sub>	0.048	0.052	1.22	1.32	3, 4
b	0.030	0.034	0.77	0.86	3, 4
b <sub>1</sub>	0.045	0.055	1.15	1.39	3, 4
c	0.018	0.022	0.46	0.55	3, 4
D	0.405	0.425	10.29	10.79	-
E	0.395	0.405	10.04	10.28	-
e	0.100 TYP		2.54 TYP		5
e <sub>1</sub>	0.200 BSC		5.08 BSC		5
H <sub>1</sub>	0.045	0.055	1.15	1.39	-
J <sub>1</sub>	0.095	0.105	2.42	2.66	6
L	0.530	0.550	13.47	13.97	-
L <sub>1</sub>	0.110	0.130	2.80	3.30	2

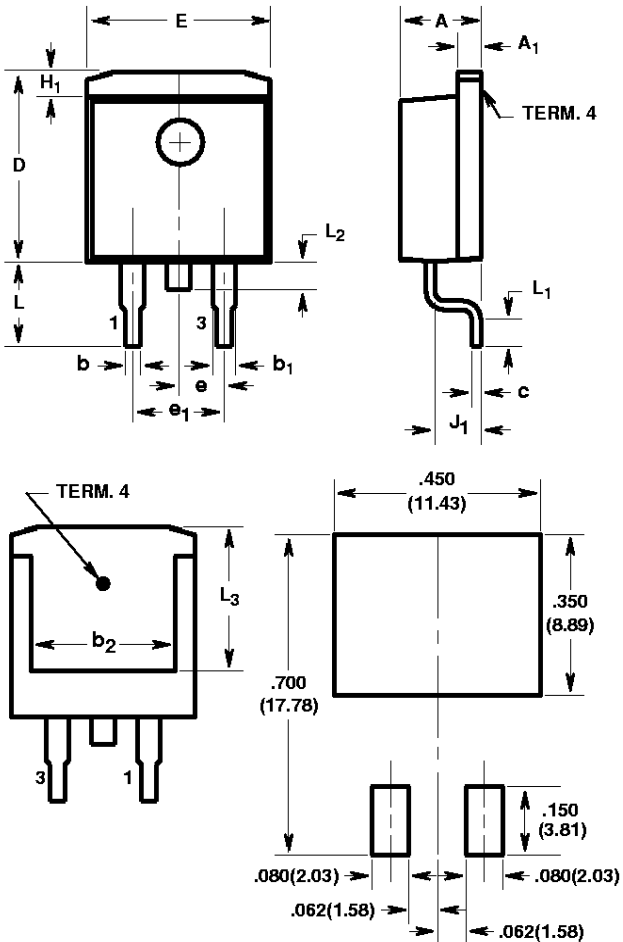
NOTES:

1. These dimensions are within allowable dimensions of Rev. A of JEDEC TO-262AA outline dated 6-90.
2. Solder finish uncontrolled in this area.
3. Dimension (without solder).
4. Add typically 0.002 inches (0.05mm) for solder plating.
5. Position of lead to be measured 0.250 inches (6.35mm) from bottom of dimension D.
6. Position of lead to be measured 0.100 inches (2.54mm) from bottom of dimension D.
7. Controlling dimension: Inch.
8. Revision 4 dated 10-95.

RFP45N02L, RF1S45N02L, RF1S45N02LSM

**TO-263AB**

SURFACE MOUNT JEDEC TO-263AB PLASTIC PACKAGE



**MINIMUM PAD SIZE RECOMMENDED FOR SURFACE-MOUNTED APPLICATIONS**

- Lead No. 1 - Gate
- Lead No. 3 - Source
- Term 4. - Drain

SYMBOL	INCHES		MILLIMETERS		NOTES
	MIN	MAX	MIN	MAX	
A	0.170	0.180	4.32	4.57	-
A <sub>1</sub>	0.048	0.052	1.22	1.32	4, 5
b	0.030	0.034	0.77	0.86	4, 5
b <sub>1</sub>	0.045	0.055	1.15	1.39	4, 5
b <sub>2</sub>	0.310	-	7.88	-	2
c	0.018	0.022	0.46	0.55	4, 5
D	0.405	0.425	10.29	10.79	-
E	0.395	0.405	10.04	10.28	-
e	0.100 TYP		2.54 TYP		7
e <sub>1</sub>	0.200 BSC		5.08 BSC		7
H <sub>1</sub>	0.045	0.055	1.15	1.39	-
J <sub>1</sub>	0.095	0.105	2.42	2.66	-
L	0.175	0.195	4.45	4.95	-
L <sub>1</sub>	0.090	0.110	2.29	2.79	4, 6
L <sub>2</sub>	0.050	0.070	1.27	1.77	3
L <sub>3</sub>	0.315	-	8.01	-	2

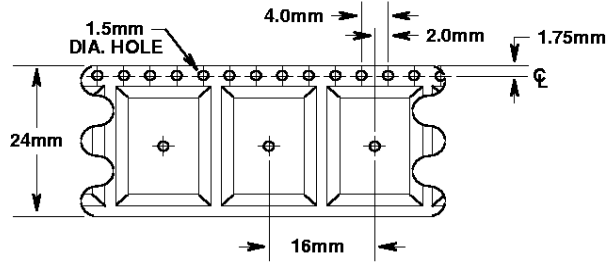
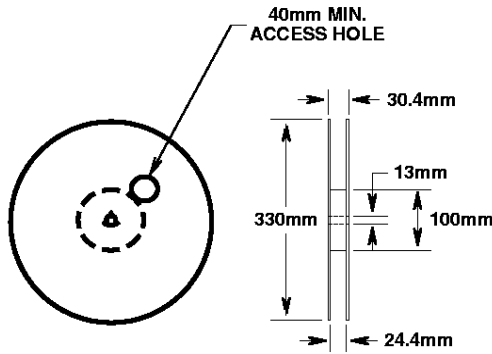
NOTES:

1. These dimensions are within allowable dimensions of Rev. C of JEDEC TO-263AB outline dated 2-92.
2. L<sub>3</sub> and b<sub>2</sub> dimensions established a minimum mounting surface for terminal 4.
3. Solder finish uncontrolled in this area.
4. Dimension (without solder).
5. Add typically 0.002 inches (0.05mm) for solder plating.
6. L<sub>1</sub> is the terminal length for soldering.
7. Position of lead to be measured 0.120 inches (3.05mm) from bottom of dimension D.
8. Controlling dimension: Inch.
9. Revision 7 dated 10-95.

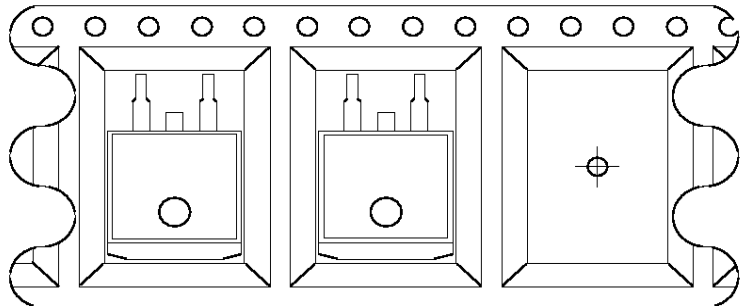
**RFP45N02L, RF1S45N02L, RF1S45N02LSM**

**TO-263AB**

24mm TAPE AND REEL



USER DIRECTION OF FEED



COVER TAPE

**GENERAL INFORMATION**

1. USE "9A" SUFFIX ON PART NUMBER.
2. 800 PIECES PER REEL.
3. ORDER IN MULTIPLES OF FULL REELS ONLY.
4. MEETS EIA-481 REVISION "A" SPECIFICATIONS.

Revision 7 dated 10-95

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